

Frequency-Domain Characterization of Power Distribution Networks

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Generic notes:

- In the errata below, missing or corrected text is highlighted in red.
- Expressions in the book without specifically stated units assume MSVA units. Where multiple units are given, MSVA is stated first, followed by optional unit in parenthesis.
- Many thanks to the readers who submitted their feedback. If you have questions or comments, or wish to notify the authors about additional errata items, please send a note to istvan.novak@ieee.org.

Chapter 1

- Pg. 5, Figure 1.3 has an extra stray vertical line in the illustration, it can be ignored.
- Pg. 8, “If we need the time-domain response of a passive, linear, and time invariant PDN, we can use (1.3) and (1.4) to calculate the time-domain noise from known noise sources.” This should read: “If we need the time-domain response of a passive, linear, and time invariant PDN, we can use **(1.2)** and **(1.3)** to calculate the time-domain noise from known noise sources.”

Chapter 2

- Pg. 16, “MATLAB is software for numerical computation and data visualization.” This should read: “MATLAB is **a** software for numerical computation and data visualization.”
- Pg. 26, Line 7 from the bottom, there is an extra **"the"**.
- Pg. 32, “In many PDN applications considered in this book, a lumped port is more appropriate, because the measurement point and is not conveniently located on the face or boundary of the structure.” This should read: “In many PDN applications considered in this book, a lumped port is more appropriate, because the measurement point **and** is not conveniently located on the face or boundary of the structure.”

Chapter 3

- Pg. 46: The "-1" in Equation 3.16 should be outside of the natural log. Thus it should read: $L=5.08*h*(\ln(2h/d)-1)$
- Pg. 48, 1st paragraph, line 9, “simplication” should be “simplification.”

Chapter 4

- Pg 69, the units and value of c (speed of light) should be specified as meters per seconds.

Chapter 5

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Chapter 6

- Pg. 167, Figure 6.13: caption (b) is missing from the upper right sketch.

Chapter 7

- Pg.198, Figure 7.1: the label port connected to Rc2 on the right side should be VNA Port 2, (instead of VNA Port 1)
- Pg. 204, line 5 from bottom: “The Venable Model 3120 covers the 10-MHz-2.4-MHz...” This should read: “The Venable Model 3120 covers the 10-**m**Hz-2.4-MHz...”
- Pg. 204, line 4 from bottom: “The AP Instruments Model 200 Parallel Frequency Response Analyzer covers 11.6-MHz -15-MHZ...” This should read: “The AP Instruments Model 200 Parallel Frequency Response Analyzer covers 11.6-**m**Hz -15-MHZ...”
- Pg. 220, clarification for caption of Figure 7.33: In the setup shown, the primary purpose of the ferrites was to minimize coupling between cables and between cables and the probe-station frame, by providing absorbing spacer elements.

Chapter 8

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Chapter 9

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